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Dimensions

Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.07mm
S	0.7mm MIN
B	0.35mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

General Information

Series	SMD Comm U2J
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	1000 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	16 VDC
Dielectric Withstanding Voltage	40 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	U2J
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	-750+/-120 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0.1% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms